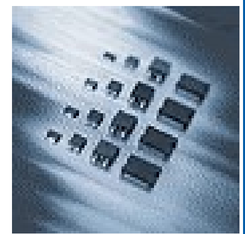

Material Content Data Sheet

Sales Product Name	BSP300 H6327	**Issued**	19. July 2018
MA#	MA001092588		
Package	PG-SOT223-4-21	**Weight***	114.06 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.019	1.77	1.77	17706	17706
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89	
	non noble metal	titanium	7440-32-6	0.051	0.04		445	
	non noble metal	chromium	7440-47-3	0.152	0.13		1334	
	non noble metal	copper	7440-50-8	50.489	44.28	44.46	442673	444541
wire	non noble metal	copper	7440-50-8	0.016	0.01	0.01	140	140
encapsulation	organic material	carbon black	1333-86-4	0.586	0.51		5141	
	plastics	epoxy resin	-	8.796	7.71		77116	
	inorganic material	silicondioxide	60676-86-0	49.255	43.19	51.41	431851	514108
leadfinish	non noble metal	tin	7440-31-5	1.464	1.28	1.28	12836	12836
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4498	4498
glue	plastics	epoxy resin	-	0.123	0.11		1080	
	noble metal	silver	7440-22-4	0.581	0.51	0.62	5091	6171
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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